

N-type-G12-R (182.3×210*272) A

Monocrystalline Wafer





The file version

PN testing machine

Phos.()

Ω -cm

Wafer inspection system

Lifetime/ μ \geq

Oxygen concentration/ppma \leq

Carbon Concentration /ppma \leq

Growth method

Etch pit density (dislocation density)/pcs/cm² \leq

Surface orientation/ $^{\circ}$

Orientation of pseudo square sides/ $^{\circ}$

Wafer model

Geometry

Wafer Side length/mm

Wafer Diameter/mm

Arc length projection/mm

Angle between adjacent sides/ $^{\circ}$

μ m

Batch mean/ μ m \geq

μ m \leq

μ m \leq

μ m \leq

μ m \leq

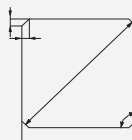
Cutting method

No visual defects (no stains no finger prints no oil no glue).

≤ 0.3 mm , Length ≤ 0.5 mm
 \leq

Naked eyes or wafer inspection system

Schematic diagram of wafer size



A.Shape/Size 182.3/210 \pm 0.25 mm

B.Diagonal 272 \pm 0.25 mm

C.Corner Length 4.72/4.07 \pm 0.5 mm

D.Right Angle 90 \pm 0.15 $^{\circ}$